

1 1. (Twice Amended) A metallurgical structure comprising:
2 a passivation layer;
3 a via through said passivation layer extending to a metal line within said metallurgical
4 structure;
5 a barrier layer lining said via;
6 a metal plug in said via above said barrier layer, wherein said metal plug and said metal
7 line comprise a same material, and wherein said metal plug, said barrier layer and said passivation
8 layer form a planar exterior surface of said metallurgical structure; and
9 a solder bump formed on said planar exterior surface.

1 8. (Twice Amended) An integrated circuit structure comprising:
2 internal components within an exterior covering;
3 a via extending through said exterior covering to said internal components;
4 a barrier layer lining said via;
5 a plug in said via above said barrier layer, wherein said plug and said internal components
6 comprise a same material, and wherein said plug and said barrier layer form a planar exterior
7 surface of said integrated circuit structure; and
8 a connector formed on said planar exterior surface.